

3. The electro-optical module according to claim 1, wherein the receptacle is disposed so as not to touch said component unit, said receptacle making contact with and being connected substantially only to said mounting surface of said substrate.

4. The electro-optical module according to claim 1, wherein said substrate has a second surface on a side thereof averted from said receptacle, and including an electronic circuit carried on said second surface.

5. The electro-optical module according to claim 1, which further comprises a cap attached directly to said mounting surface of said substrate for electrically shielding said component unit.

6. The electro-optical module according to claim 1, wherein said substrate forms a part of a rigid-flexible-rigid circuit carrier.

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